

# New Co-packaged Photonics



## Overview

Co-Packaged Optics (CPO) is emerging as a transformative solution. By integrating optical engines closer to switch ASICs and GPUs through advanced packaging approaches such as 2.5D and 3D, advanced semiconductor processes such as hybrid bonding and heterogeneous integration are key. These pressures are driving renewed momentum behind co-packaged optics (CPO). According to LightCounting, sales of lasers and photonic integrated circuits for optical transceivers are expected to grow from \$2.9B by 2029, fueled largely by AI data centers. This paper explores the evolution of CPO performance from various perspectives, including fan-out wafer level. NVIDIA is developing a co-packaged optics (CPO) platform that integrates optical and electrical components to improve data-center connectivity, in collaboration with industry partners like TSMC. (NYSE: COHR), a global leader in photonics, today announced it will demonstrate multiple co-packaged optics (CPO) technologies at OFC 2026 in Los Angeles, highlighting the company's broad portfolio and vertical technology stack.



## Article Content

GlobalFoundries Announces New Co-Packaged Optics Solution for AI

GlobalFoundries (GF) announced the introduction of its SCALE™ optical module solution for co-packaged optics (CPO). GF's Silicon photonics Co-packaged Advanced Light Engine (SCALE)

Co-Packaged Optics (CPO) Co-Packaged Optics (CPO)

Co-packaged optics overcomes these limitations by placing the optical engine much closer to the switching silicon. Its success depends on advanced semiconductor

The Silicon Photonics & Co-Packaged Optics supply chain

Map of 90+ companies in the co-packaged optics supply chain. SOITEC, EV Group, Siviers Photonics, IQE, Sumitomo Electric, Lumentum, Coherent, NVIDIA etc

Demonstration of Silicon-Photonics Hybrid Glass-Epoxy

Abstract—To realize a new package substrate for co-packaged optics, a silicon-photonics hybrid glass-epoxy substrate was demonstrated. In the substrate, silicon photonics dies working as ...

Five Key Trends of Co-Packaged Optics (CPO) in 2026

These pressures are driving renewed momentum behind co-packaged optics (CPO). According to LightCounting, sales of lasers and

Lambda Leads Early Adoption of NVIDIA Co-Packaged

"NVIDIA Quantum-X Photonics is the foundation for high-performance, resilient AI networks. It delivers superior power efficiency,

Heterogeneous Integration Technology Drives the

As the TGV process matures and its cost continues to decline, it is expected to become the mainstream CPO packaging path, propelling silicon

CPO Emerges as the New Sought-After as

On January 21, JCET announced a major breakthrough in its co-packaged optics (Co-Packaged Optics, CPO) technology development. Silicon

How Industry Collaboration Fosters NVIDIA Co

NVIDIA is developing a co-packaged optics (CPO) platform that integrates optical and electrical components to improve data-center connectivity,

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Co-Packaged Optics Market Analysis, Dynamics 2026-2036

Global Co-packaged Optics Market Research Report Covers: Market segmentation and segment-wise market breakdown highlight demand across high-speed optical interconnects, photonic integration

Co-Packaged Optics: powering the next wave of AI infrastructures

Get the news on Co-Packaged Optics powering the next wave of AI. Explore photonics packaging trends and join our live with Lam Research.

Co-Packaged Optics (CPO)Co-Packaged Optics (CPO)

At GTC 2025, NVIDIA introduced two new networking switch platforms, Spectrum X Photonics and Quantum X Photonics, both built on co packaged optics. Central

Intel® Silicon Photonics

Intel® Silicon Photonics combines the manufacturing scale and capability of silicon with the power of light onto a single chip.

How Industry Collaboration Fosters NVIDIA Co

Join us as we take an in-depth look at the innovation, partnerships, and technical foundations behind the NVIDIA co-packaged optics (CPO)

NVIDIA Unveils Revolutionary Photonics Switches for

NVIDIA has unveiled groundbreaking networking technology with the announcement of Spectrum-X and Quantum-X silicon photonics networking

Estonia co packaged photonics 25g Munich, Nuremberg and Bavaria

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NVIDIA announces spectrum-X photonics, co

NVIDIA unveiled NVIDIA Spectrum-X™ and NVIDIA Quantum-X silicon photonics networking switches, which enable AI factories to connect

NewPhotonics optical IC chips for the AI scale data center

All-Optical Photonic ICs Designed for Scale Highly integrated photonic integrated circuit chips designed for transceiver pluggable and co-packaged optics. Built for

Scaling Power-Efficient AI Factories with NVIDIA

Spectrum-X Ethernet Photonics, integrated into the NVIDIA Rubin platform, delivers co-packaged optics and silicon photonic engines with 5x

Where co-packaged optics (CPO) technology stands in 2026

Co-packaged optics (CPO) technology, a key enabler for next-generation data center architectures, promises unprecedented bandwidth density and power efficiency by tightly integrating

LIVE WEBINAR | CO-PACKAGED OPTICS: POWERING THE NEXT

Scaling photonics packaging to meet high-volume production demands requires bridging a fundamental gap: making photonic architectures fully compatible with mainstream microelectronics processes

Coherent Demonstrates Multiple Technologies for Co

These demonstrations highlight Coherent's ability to support multiple optical architectures for co-packaged optics, leveraging its expertise across key

## Contact Us

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